



### General Description

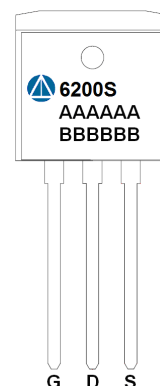
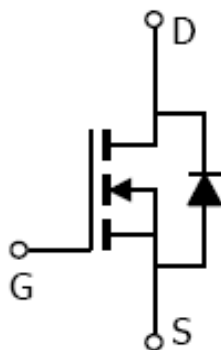
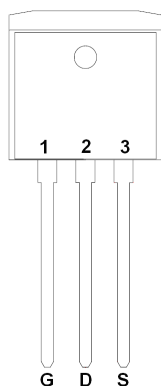
AFN6200S, N-Channel enhancement mode MOSFET, uses Advanced Trench Technology to provide excellent  $R_{DS(ON)}$ , low gate charge.

These devices are particularly suited for low voltage power management, and low in-line power loss are needed in commercial industrial surface mount applications.

### Features

- 100V/50A,  $R_{DS(ON)}=5.8m\Omega@V_{GS}=10V$
- 100V/20A,  $R_{DS(ON)}=8.5m\Omega@V_{GS}=5V$
- Super high density cell design for extremely low  $R_{DS(ON)}$
- TO-262 package design

### Pin Description ( TO-262 )



### Application

- Power Supply - Secondary Synchronous Rectification
- Industrial
- Primary Switch

### Pin Define

Pin	Symbol	Description
1	G	Gate
2	D	Drain
3	S	Source

### Ordering Information

Part Ordering No.	Part Marking	Package	Unit	Quantity
AFN6200ST262TG	6200S AAAAAA BBBBBB	TO-262	Tube	50 EA

- ※ A Lot code
- ※ B Date code
- ※ AFN6200ST262TG : Tube ; Pb- Free ; Halogen -Free



**Absolute Maximum Ratings**

(T<sub>A</sub>=25°C Unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DSS</sub>	100	V
Gate –Source Voltage	V <sub>GSS</sub>	±20	V
Continuous Drain Current(T <sub>J</sub> =150°C)	I <sub>D</sub>	T <sub>c</sub> =25°C	120
		T <sub>c</sub> =70°C	90
Pulsed Drain Current	I <sub>DM</sub>	400	A
Continuous Source Current(Diode Conduction)	I <sub>S</sub>	100	
Single Pulse Avalanche Current	I <sub>AS</sub>	70	
Power Dissipation	P <sub>D</sub>	75	W
Operating Junction Temperature	T <sub>J</sub>	150	°C
Storage Temperature Range	T <sub>STG</sub>	-55/150	°C
Thermal Resistance-Junction to Ambient	R <sub>θJA</sub>	62.5	°C/W

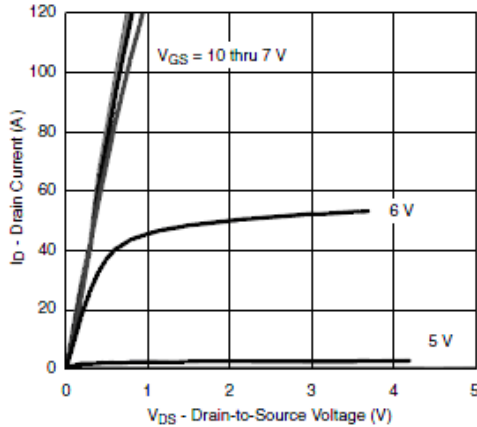
**Electrical Characteristics**

(T<sub>A</sub>=25°C Unless otherwise noted)

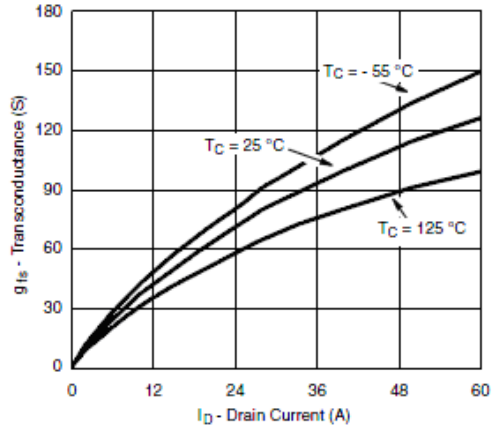
Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
<b>Static</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	100			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA	2.0		4.0	
Gate Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =80V, V <sub>GS</sub> =0V			1	uA
		V <sub>DS</sub> =80V, V <sub>GS</sub> =0V T <sub>J</sub> =85°C			30	
On-State Drain Current	I <sub>D(on)</sub>	V <sub>DS</sub> ≥ 10V, V <sub>GS</sub> =10V	70			A
Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =50A		4.6	5.8	mΩ
		V <sub>GS</sub> =5V, I <sub>D</sub> =20A		6.5	8.5	
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =15V, I <sub>D</sub> =20A		62		S
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =30A, V <sub>GS</sub> =0V		0.8	1.3	V
<b>Dynamic</b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =50V, V <sub>GS</sub> =10V I <sub>D</sub> ≅85A		95	115	nC
Gate-Source Charge	Q <sub>gs</sub>			45		
Gate-Drain Charge	Q <sub>gd</sub>			35		
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> =50V, V <sub>GS</sub> =0V f=1MHz		6250		pF
Output Capacitance	C <sub>oss</sub>			580		
Reverse Transfer Capacitance	C <sub>rss</sub>			235		
Turn-On Time	t <sub>d(on)</sub>	V <sub>DD</sub> =50V, R <sub>L</sub> =0.6Ω I <sub>D</sub> ≅85A, V <sub>GEN</sub> =10V R <sub>G</sub> =1Ω		32	65	ns
	t <sub>r</sub>			25	55	
Turn-Off Time	t <sub>d(off)</sub>			40	80	
	t <sub>f</sub>			15	40	



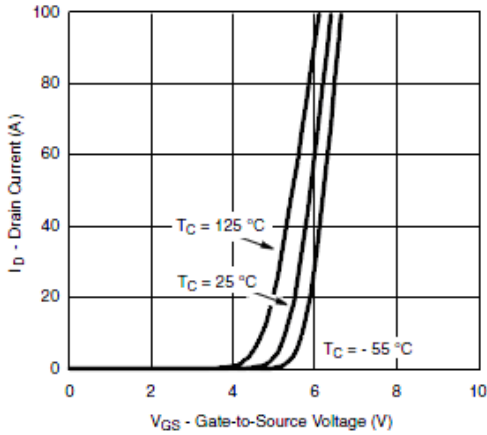
## Typical Characteristics



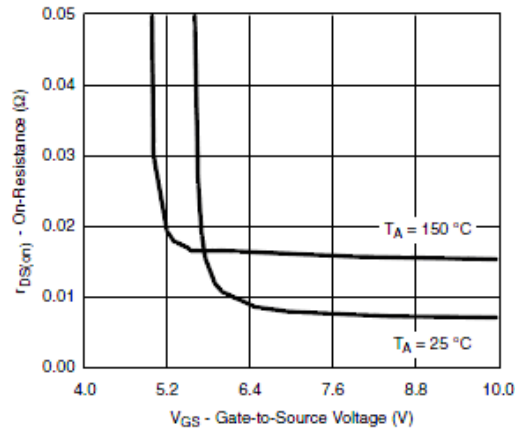
Output Characteristics



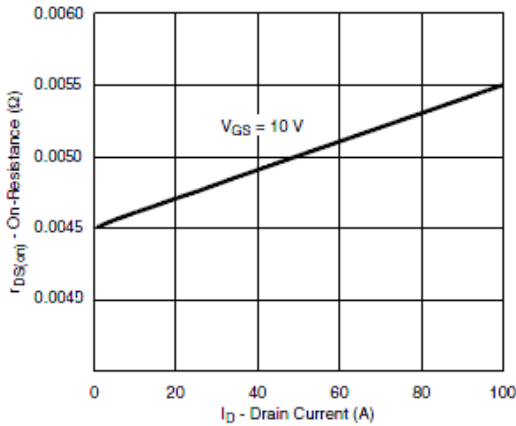
Transconductance



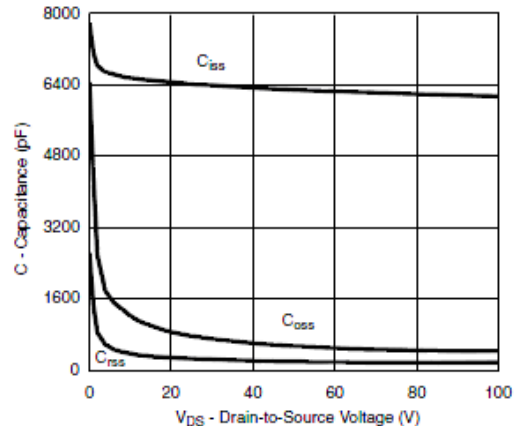
Transfer Characteristics



On-resistance vs. Gate-to-Source Voltage



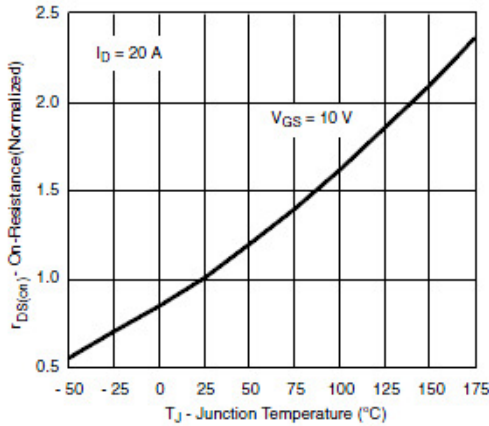
On-Resistance vs. Drain Current



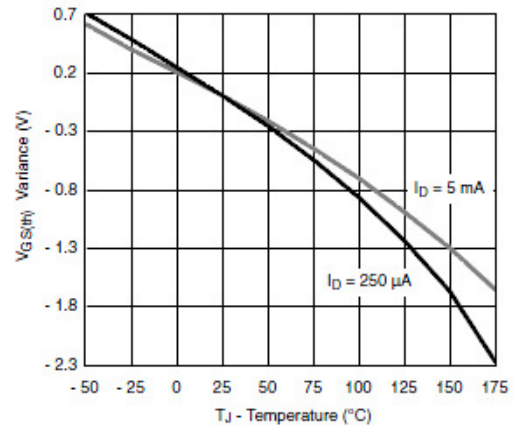
Capacitance



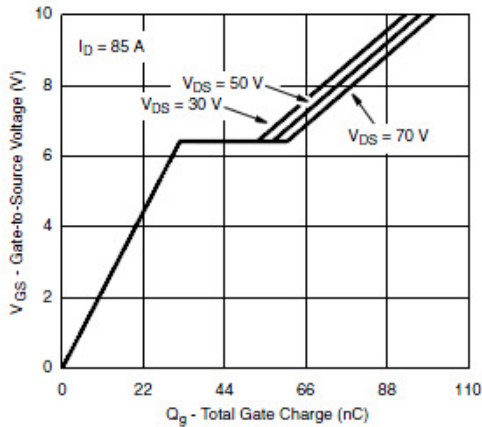
## Typical Characteristics



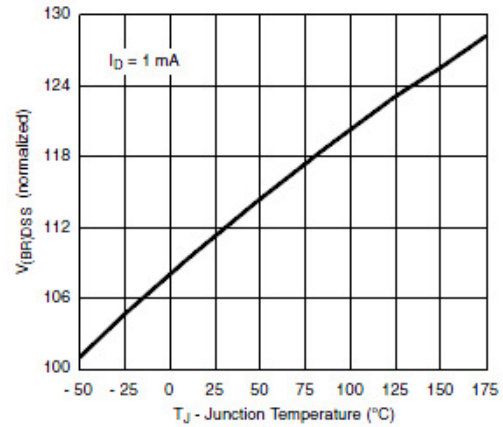
On-Resistance vs. Junction Temperature



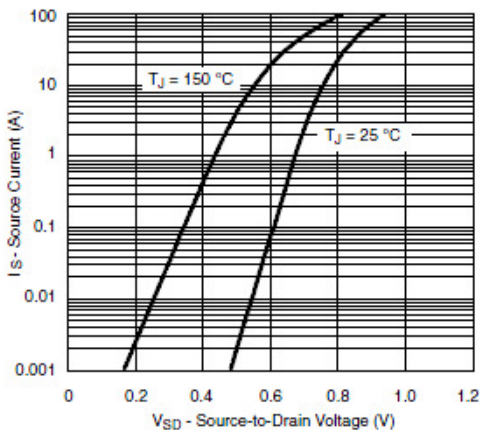
Threshold Voltage



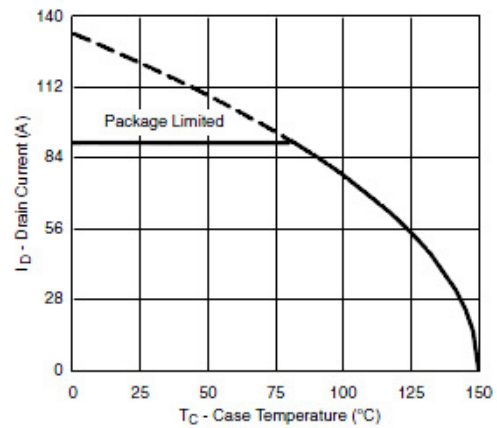
Gate Charge



Drain Source Breakdown vs. Junction Temperature



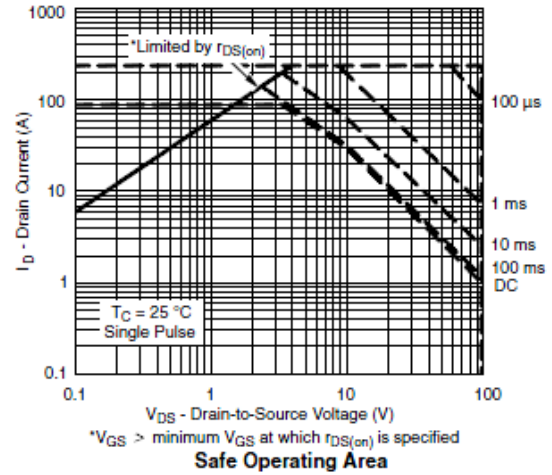
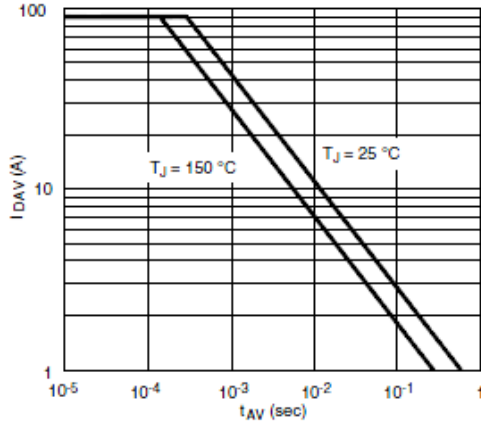
Source-Drain Diode Forward Voltage



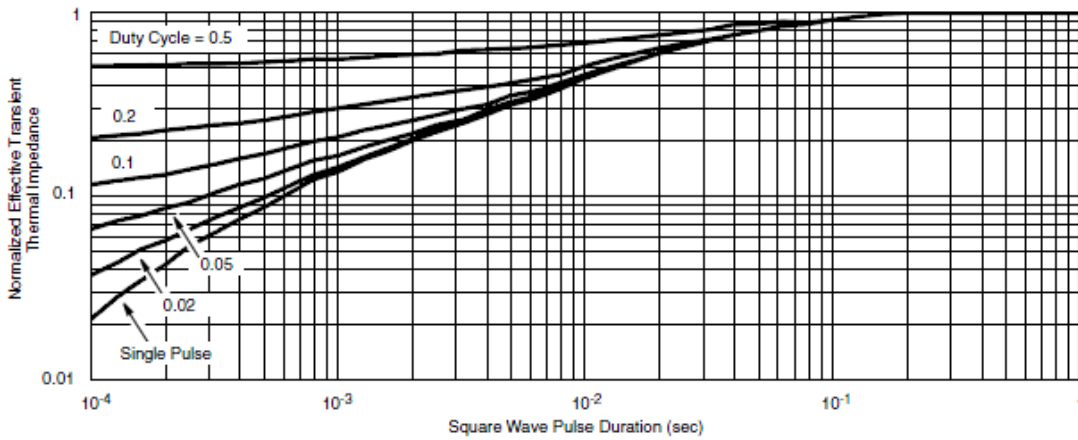
Maximum Drain Current vs. Case Temperature



## Typical Characteristics



Single Pulse Avalanche Current Capability vs. Time

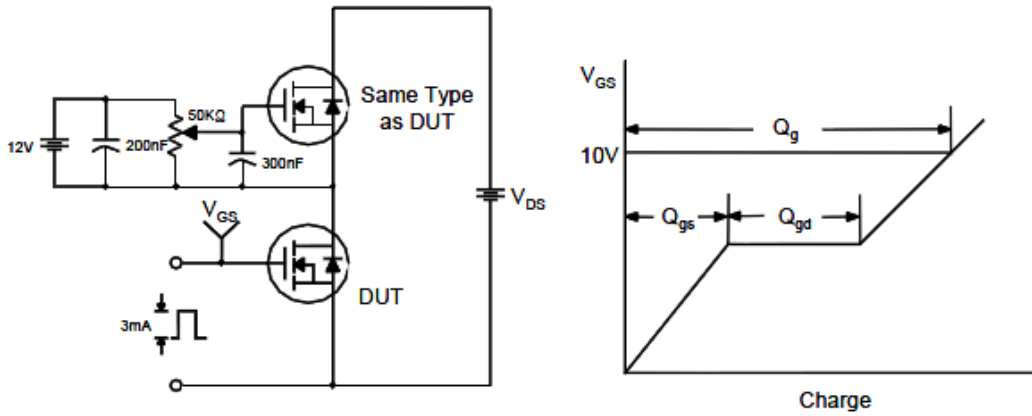


Normalized Thermal Transient Impedance, Junction-to-Case

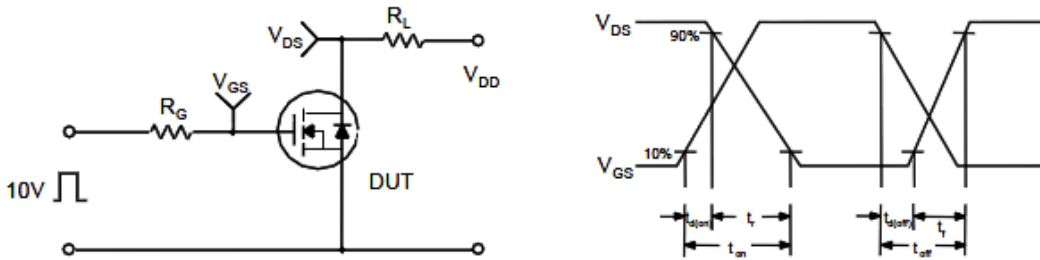


**Typical Characteristics**

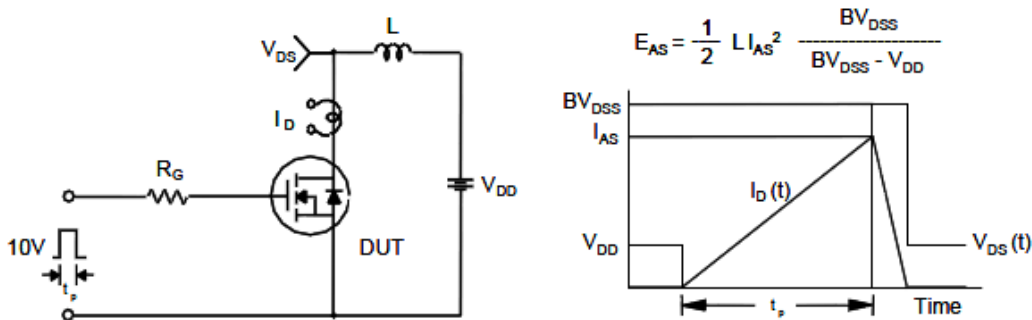
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms

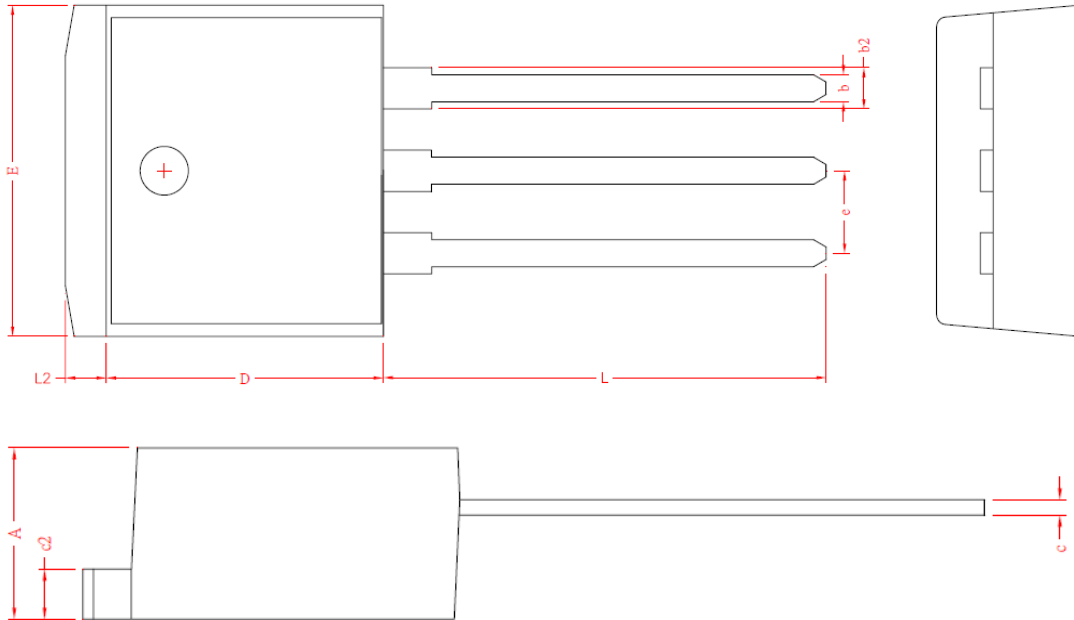


Unclamped Inductive Switching Test Circuit & Waveforms





**Package Information ( TO-262 )**



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	4.40	4.80	c2	1.25	1.45
b	0.76	1.0	b2	1.17	1.47
D	8.6	9.0	L	13.25	14.25
c	0.36	0.50	e	2.54 REF.	
E	9.80	10.4	L2	1.27 REF.	

©2010 Alfa-MOS Technology Corp.  
 2F, No.80, Sec.1, Cheng Kung Rd., Nan Kang Dist., Taipei City 115, Taiwan (R.O.C.)  
 Tel : 886 2) 2651 3928  
 Fax : 886 2) 2786 8483  
 ©<http://www.alfa-mos.com>